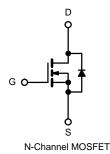


### SW070R08VT-VB Datasheet

N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) Max.	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
	0.0064 at V <sub>GS</sub> = 10 V	75 <sup>a</sup>			
80	0.0070 at V <sub>GS</sub> = 6.0 V	65 <sup>a</sup>	17.1 nC		
	0.0087 at V <sub>GS</sub> = 4.5 V	55 <sup>a</sup>			



#### FEATURES

- Trench Power MOSFET
- 100 %  $\rm R_g$  and UIS Tested

#### **APPLICATIONS**

- Primary Side Switching
- Synchronous Rectification
- DC/AC Inverters
- LED Backlighting



# 

TO-251

G D S Top View

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	80		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V	
	T <sub>C</sub> = 25 °C		75 <sup>a</sup>	A
	T <sub>C</sub> = 70 °C		62.7 <sup>a</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	28.6 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		24.9 <sup>b, c</sup>	
Pulsed Drain Current (t = 100 µs)	•	I <sub>DM</sub>	350	
	T <sub>C</sub> = 25 °C		75 <sup>a</sup>	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	4.5 <sup>b, c</sup>	
Single Pulse Avalanche Current		I <sub>AS</sub>	30	
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	45	mJ
	T <sub>C</sub> = 25 °C		62.5	w
	T <sub>C</sub> = 70 °C		40	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	PD	5 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		3.2 <sup>b, c</sup>	
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		
Soldering Recommendations (Peak Temperatur	<u> </u>	260		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, f</sup>	$t \le 10 s$	R <sub>thJA</sub>	20	25	°C/W		
Maximum Junction-to-Case (Drain)	Steady State	R <sub>thJC</sub>	1.5	2.0	0/11		

#### Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

- d. The TO-220 is a leadless package. The end of the lead terminal is exposed
- copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 70 °C/W.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	80			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 A		37			
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μΑ		- 6.1		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th</sub> )	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.4		2.6	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	75			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.0064			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 15 A		0.0070		Ω	
	. ,	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		0.0087			
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		60		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1855			
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = 40 V, $V_{GS}$ = 0 V, f = 1 MHz		950		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			76			
Total Gate Charge	Qg	$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		35.5	54	_	
		$V_{DS} = 40 \text{ V}, V_{GS} = 6 \text{ V}, I_D = 10 \text{ A}$		22	33		
				17.1	26	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		5.3			
Gate-Drain Charge	Q <sub>gd</sub>			7.3			
Output Charge	Q <sub>oss</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$		57	86		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.5	1.3	2	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			12	24		
Rise Time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, \text{ R}_{L} = 4 \Omega$		8	16		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 10 \text{ Å}, V_{\text{GEN}} = 10 \text{ V}, R_g = 1 \Omega$		32	64	1	
Fall Time	t <sub>f</sub>			7	14		
Turn-On Delay Time	t <sub>d(on)</sub>			14	28	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 40 \text{ V}, \text{ R}_{\text{I}} = 4 \Omega$		11	22		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 6.0 \text{ V}, R_g = 1 \Omega$		30	60		
Fall Time	t <sub>f</sub>			8	16		
Drain-Source Body Diode Characteristic	s				•		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			75	۸	
Pulse Diode Forward Current (t = 100 µs)	I <sub>SM</sub>				150	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A		0.76	1.1	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			38	75	ns	
Body Diode Reverse Recovery Charge	everse Recovery Charge Qr			36	70	nC	
Reverse Recovery Fall Time	ta	—— I <sub>F</sub> = 10 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		19		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			19			

#### Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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- 55 °C

7.0

5.6

=

4.2

36

 $V_{GS} = 10 V$ 

75

**On-Resistance vs. Junction Temperature** 

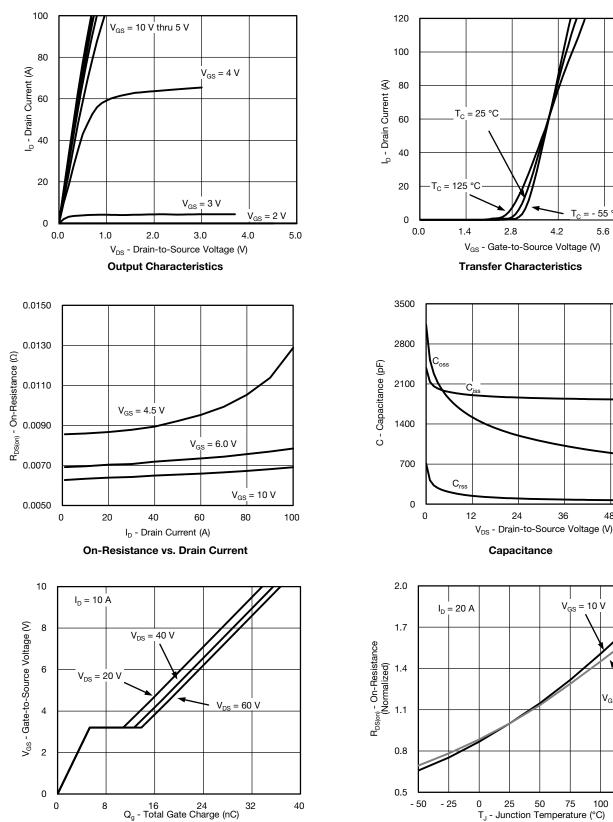
100

48

V<sub>GS</sub> = 4.5 V

125

60



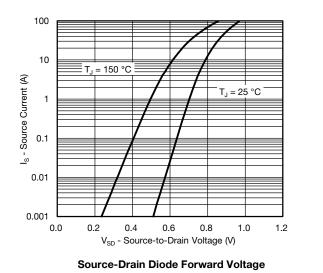
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

服务热线:400-655-8788

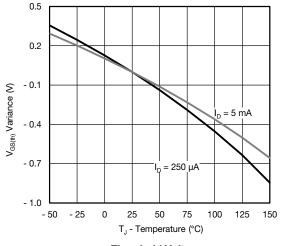
**Gate Charge** 

150

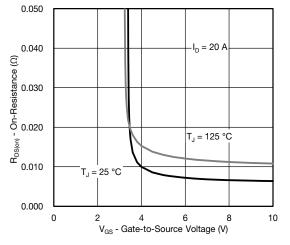




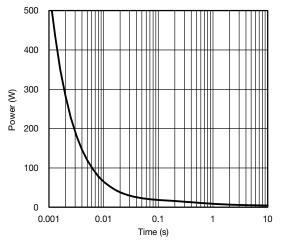
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



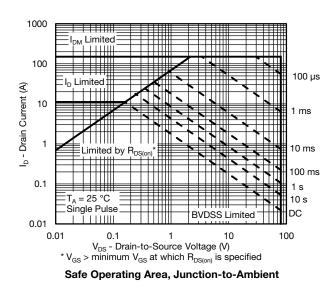




**On-Resistance vs. Gate-to-Source Voltage** 

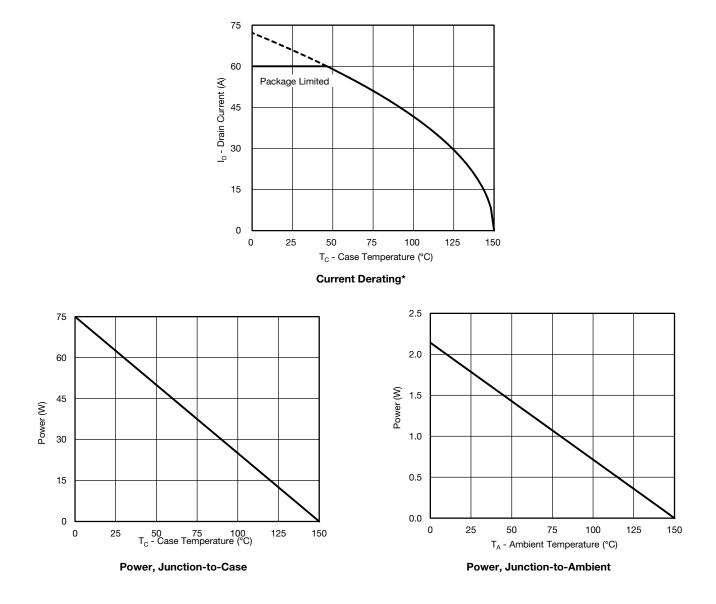


Single Pulse Power, Junction-to-Ambient





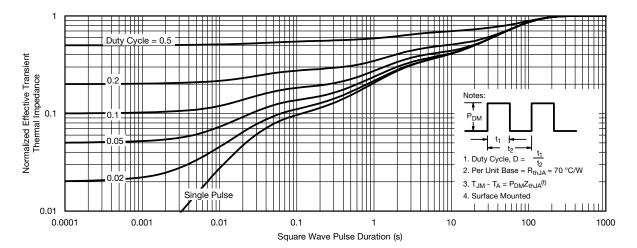
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



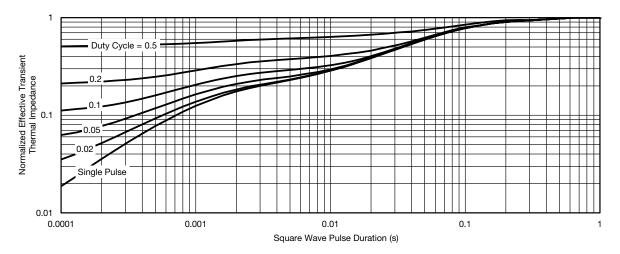
\* The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



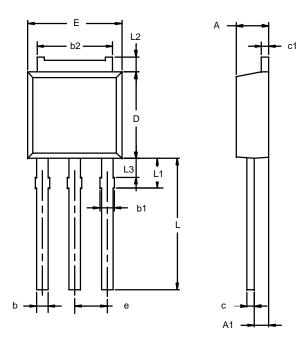




Normalized Thermal Transient Impedance, Junction-to-Case



#### TO-251AA (DPAK)



	MILLIM	IETERS	INCHES		
Dim	Min Max		Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

Note: Dimension L3 is for reference only.



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